

## QF2018M

*No Clean Liquid Flux*



### Product Description

QF2018M is a very low solid content flux, designed for spraying application. QF2018M is halide-free and gives excellent soldering performance on various metal surface finishes. This no-clean and clear residue flux shows superior wetting characteristic and reduces micro-solderballs during wave soldering. It is compatible with lead free applications.

### Application

QF2018M is specially formulated for spraying as well as dipping process. Recommended onboard preheat temperature is 80 – 110°C.

### Residue Removal

Since the residues are minimal and non-corrosive, removal is usually not required. If cleaning is required, the flux residue could be removed by any solvent or aqueous flux cleaner available in the market.

### Recommended Solvent

Asahi's complementary Solvent #2000. Solvent can be stored for about 2 year under normal storage conditions of 25°C.

### Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

### Storage

Under proper storage condition, QF2018M can be stored for up to 6 months. QF2018M is flammable. Keep away from all sources of heat, sparks, flame and sunlight.

### Packaging

Available in 18kg/carboy.

### Specification

Item	Result
State	Clear and transparent liquid
Colour	Colourless
Specific Gravity @ 25°C	0.788 +/- 0.005
<small>JIS Z 3197 8.2.2</small>	
Non-volatile Solid Content (110°C, 1hr)	2.2 +/- 0.2 wt%
<small>JIS Z 3197 8.1.3</small>	
Halide Content	Not added
<small>JIS Z 3197 8.1.4.2.1</small>	
Acid Value Test	12.5 +/- 2 mg KOH/g flux
<small>IPC-TM-650 2.3.13</small>	
<small>JIS Z 3197 8.1.4.1</small>	
Water Extract Resistivity	> 1 x 10 <sup>4</sup> Ω-cm
<small>JIS Z 3197 8.1.1</small>	
Surface Insulation Resistance (85°C, 85%RH, 168hrs)	> 1 x 10 <sup>8</sup> Ω, Pass
<small>IPC-TM-650 2.6.3.3</small>	
Electromigration (85°C, 88.5%RH, 596hrs)	Pass
<small>IPC-TM-650 2.6.14.1</small>	
Copper Corrosion Test	Pass
<small>IPC-TM-650 2.6.15</small>	
<small>JIS Z 3197 8.4.1</small>	
Copper Mirror Test	Classified as "M", Pass
<small>IPC-TM-650 2.3.32</small>	
<small>JIS Z 3197 8.4.2</small>	
Flux Activity Classification	ROM0
<small>IPC J-STD-004</small>	
Spread Factor	> 70% (SCS7)
<small>JIS Z 3197 8.3.1.1</small>	
Residue Dryness Test	Dry
<small>IPC-TM-650 2.4.47</small>	
<small>JIS Z 3197 8.5.1</small>	
Surface Finish	Shiny

#### DISCLAIMER OF LIABILITY

"All statements, information and recommendations contained in this catalog are based on data and test results which we consider, to the best of our knowledge and belief, to be reliable and informative to the users but the accuracy and completeness thereof is not guaranteed. No warranty, expressed or implied, statutory or otherwise, is given regarding the use of the information and products contained in this catalog since the conditions and suitability for use, handlings, storage or possession of the products are determined by the users and are therefore beyond our control. We shall not be liable in respect of any liabilities, losses (including consequential losses), damages, proceedings, costs, claims or injuries whatsoever sustained or suffered by the users (including any third parties) in connection with the use of the information, recommendation and the products contained in this catalog."

**Singapore Asahi Chemical and Solder Industries Pte Ltd**  
 47 Pandan Road Singapore 609288  
 Tel: +65 6262-1616 Fax: +65 6261-6311  
 Website: <http://www.asahisolder.com> Email: [enquiry@sinasahi.com.sg](mailto:enquiry@sinasahi.com.sg)